

## Dual N-Channel Enhancement Mode Power MOSFET

### Description

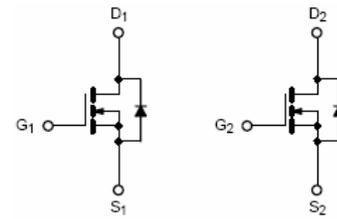
The HM4826 uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

### General Features

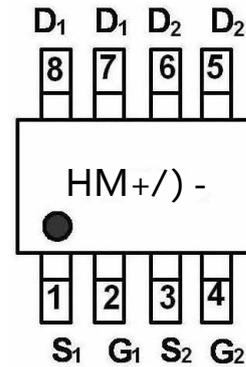
- $V_{DS} = 60V, I_D = 9A$   
 $R_{DS(ON)} < 16m\Omega @ V_{GS}=10V$  (Typ:12m $\Omega$ )
- High density cell design for ultra low  $R_{dson}$
- Fully characterized avalanche voltage and current
- Low gate to drain charge to reduce switching losses

### Application

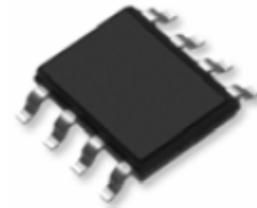
- Power switching application
- Load switch



Schematic diagram



Marking and pin Assignment



SOP-8 top view

### Package Marking and Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity |
|----------------|--------|----------------|-----------|------------|----------|
| HM4826         | HM4826 | SOP-8          | -         | -          | -        |

### Absolute Maximum Ratings ( $T_C=25^\circ C$ unless otherwise noted)

| Parameter  | Symbol             | Limit      | Unit       |
|--|--------------------|------------|------------|
| Drain-Source Voltage                             | $V_{DS}$           | 60         | V          |
| Gate-Source Voltage                              | $V_{GS}$           | $\pm 20$   | V          |
| Drain Current-Continuous                         | $I_D$              | 9          | A          |
| Drain Current-Continuous( $T_C=100^\circ C$ )    | $I_D(100^\circ C)$ | 6          | A          |
| Pulsed Drain Current                             | $I_{DM}$           | 40         | A          |
| Maximum Power Dissipation                        | $P_D$              | 3.1        | W          |
| Operating Junction and Storage Temperature Range | $T_J, T_{STG}$     | -55 To 150 | $^\circ C$ |

### Thermal Characteristic

|   |                 |    |              |
|---|-----------------|----|--------------|
| Thermal Resistance, Junction-to-Ambient <sup>(Note 2)</sup> | $R_{\theta JA}$ | 40 | $^\circ C/W$ |
|---|-----------------|----|--------------|

### Electrical Characteristics (TC=25°C unless otherwise noted)

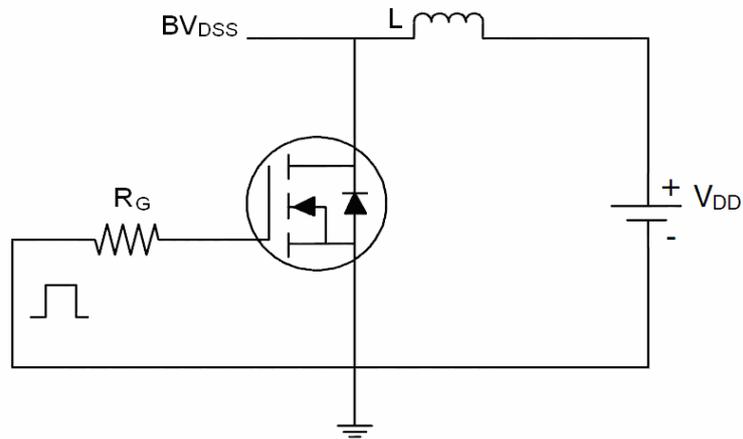
| Parameter                                 | Symbol       | Condition  | Min | Typ  | Max       | Unit       |
|---|--------------|--|-----|------|-----------|------------|
| <b>Off Characteristics</b>                |              |  |     |      |           |            |
| Drain-Source Breakdown Voltage            | $BV_{DSS}$   | $V_{GS}=0V, I_D=250\mu A$  | 60  |      | -         | V          |
| Zero Gate Voltage Drain Current           | $I_{DSS}$    | $V_{DS}=60V, V_{GS}=0V$  | -   | -    | 1         | $\mu A$    |
| Gate-Body Leakage Current                 | $I_{GSS}$    | $V_{GS}=\pm 20V, V_{DS}=0V$  | -   | -    | $\pm 100$ | nA         |
| <b>On Characteristics</b> (Note 3)        |              |  |     |      |           |            |
| Gate Threshold Voltage                    | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=250\mu A$  | 2   | 3    | 4         | V          |
| Drain-Source On-State Resistance          | $R_{DS(ON)}$ | $V_{GS}=10V, I_D=9A$   | -   | 12   | 16        | m $\Omega$ |
| Forward Transconductance                  | $g_{FS}$     | $V_{DS}=5V, I_D=9A$  | 20  | -    | -         | S          |
| <b>Dynamic Characteristics</b> (Note 4)   |              |  |     |      |           |            |
| Input Capacitance                         | $C_{ISS}$    | $V_{DS}=30V, V_{GS}=0V,$<br>$F=1.0MHz$                               | -   | 2800 | -         | PF         |
| Output Capacitance                        | $C_{OSS}$    |  | -   | 430  | -         | PF         |
| Reverse Transfer Capacitance              | $C_{RSS}$    |  | -   | 190  | -         | PF         |
| <b>Switching Characteristics</b> (Note 4) |              |  |     |      |           |            |
| Turn-on Delay Time                        | $t_{d(on)}$  | $V_{DD}=30V, R_L=1\Omega$<br>$V_{GS}=10V, R_{GEN}=3\Omega$           | -   | 8    | -         | nS         |
| Turn-on Rise Time                         | $t_r$        |  | -   | 6    | -         | nS         |
| Turn-Off Delay Time                       | $t_{d(off)}$ |  | -   | 30   | -         | nS         |
| Turn-Off Fall Time                        | $t_f$        |  | -   | 5    | -         | nS         |
| Total Gate Charge                         | $Q_g$        | $V_{DS}=30V, I_D=9A,$<br>$V_{GS}=10V$                                | -   | 45   | -         | nC         |
| Gate-Source Charge                        | $Q_{gs}$     |  | -   | 10   | -         | nC         |
| Gate-Drain Charge                         | $Q_{gd}$     |  | -   | 15   | -         | nC         |
| <b>Drain-Source Diode Characteristics</b> |              |  |     |      |           |            |
| Diode Forward Voltage (Note 3)            | $V_{SD}$     | $V_{GS}=0V, I_S=9A$  | -   | -    | 1.2       | V          |
| Diode Forward Current (Note 2)            | $I_S$        | -  | -   | -    | 9         | A          |
| Reverse Recovery Time                     | $t_{rr}$     | $T_J = 25^\circ C, I_F = 9A$<br>$di/dt = 100A/\mu s$ (Note 3)        | -   | 41   | -         | nS         |
| Reverse Recovery Charge                   | $Q_{rr}$     |  | -   | 51   | -         | nC         |
| Forward Turn-On Time                      | $t_{on}$     | Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD) |     |      |           |            |

#### Notes:

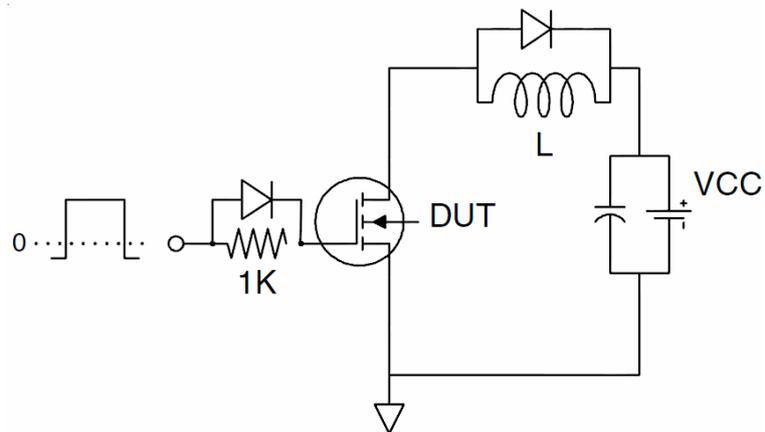
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

## Test Circuit

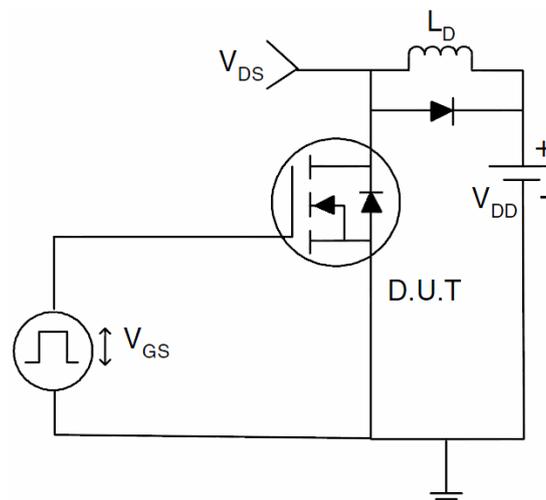
### 1) $E_{AS}$ test Circuit



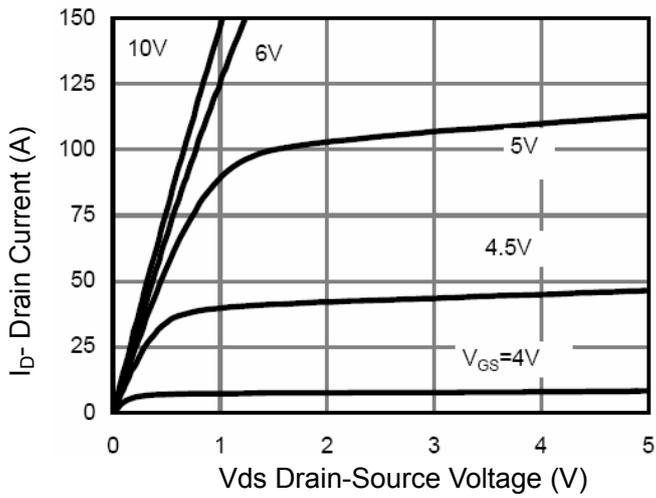
### 2) Gate charge test Circuit



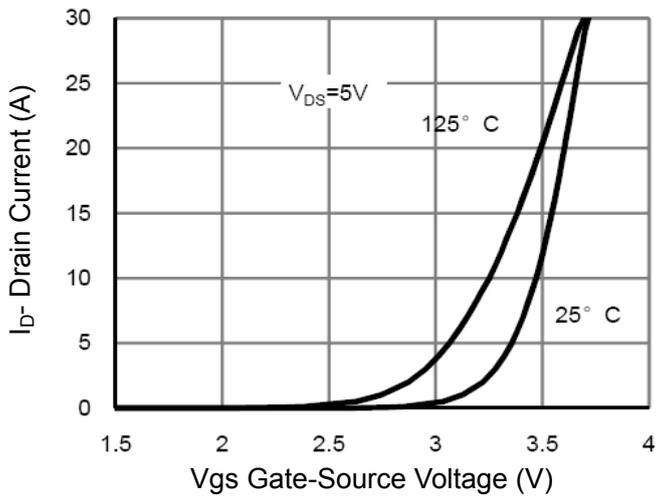
### 3) Switch Time Test Circuit



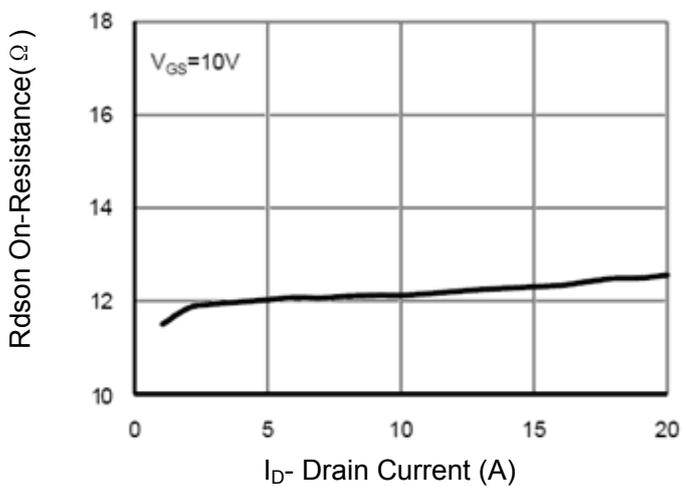
## Typical Electrical and Thermal Characteristics (Curves)



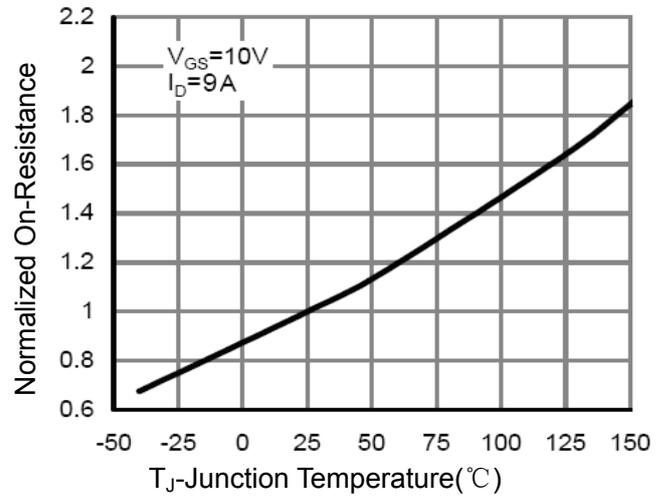
**Figure 1 Output Characteristics**



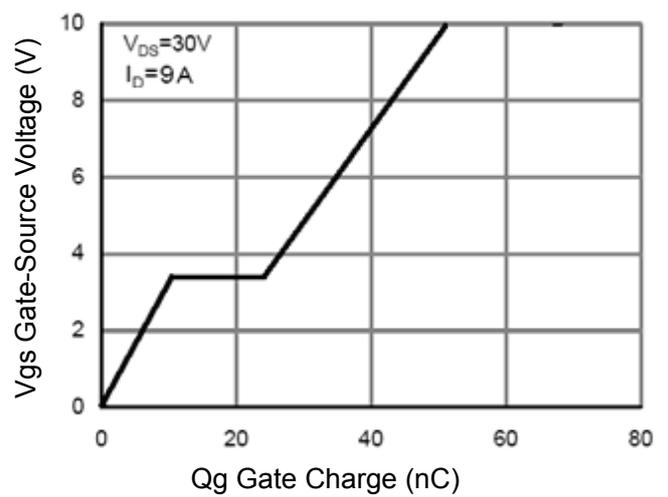
**Figure 2 Transfer Characteristics**



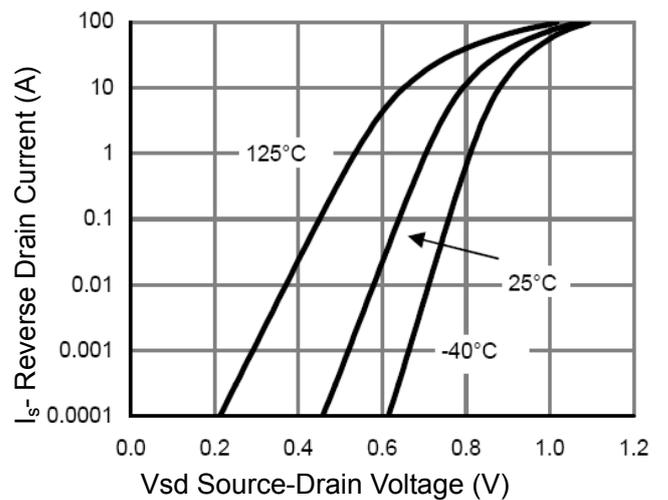
**Figure 3 Rdson- Drain Current**



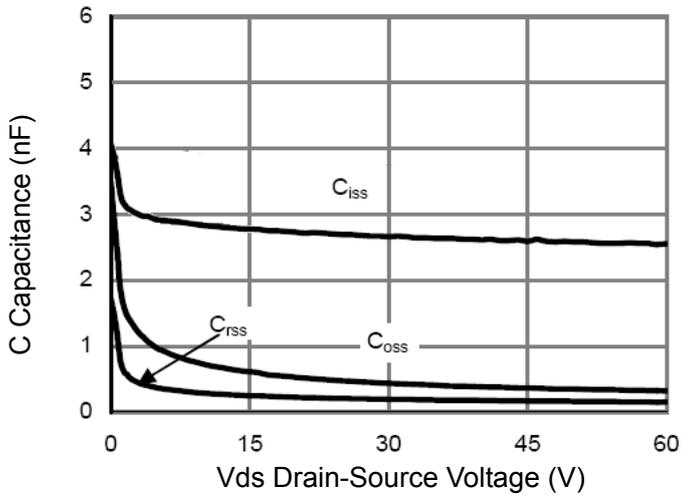
**Figure 4 Rdson-Junction Temperature**



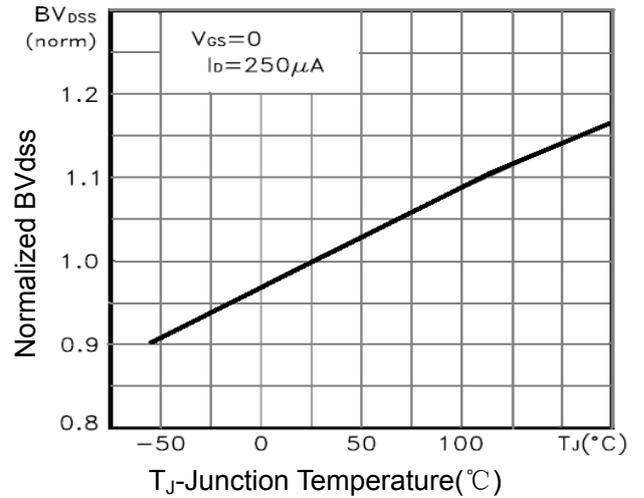
**Figure 5 Gate Charge**



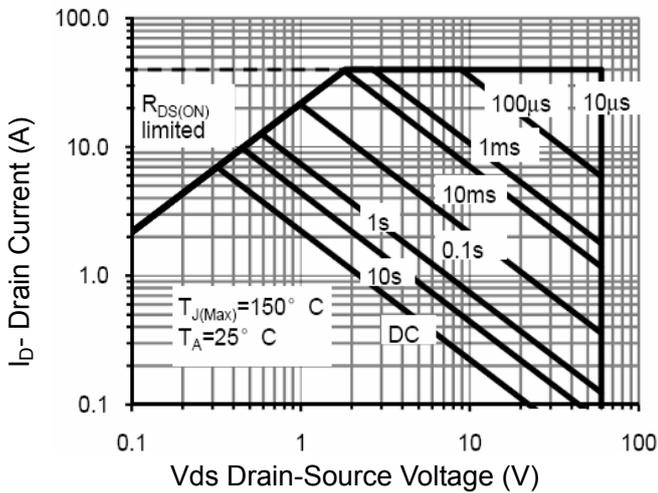
**Figure 6 Source- Drain Diode Forward**



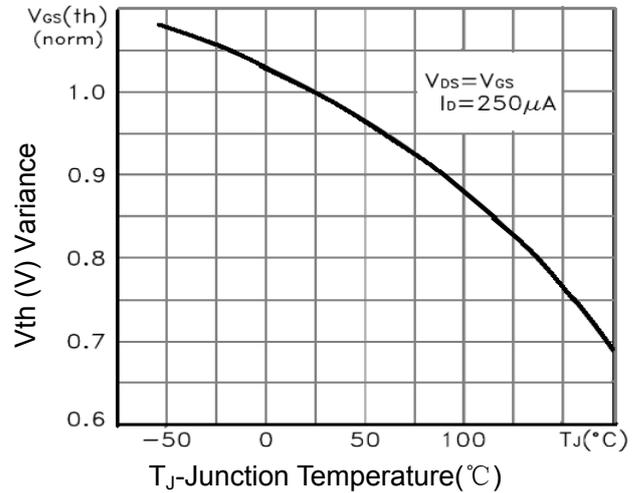
**Figure 7 Capacitance vs Vds**



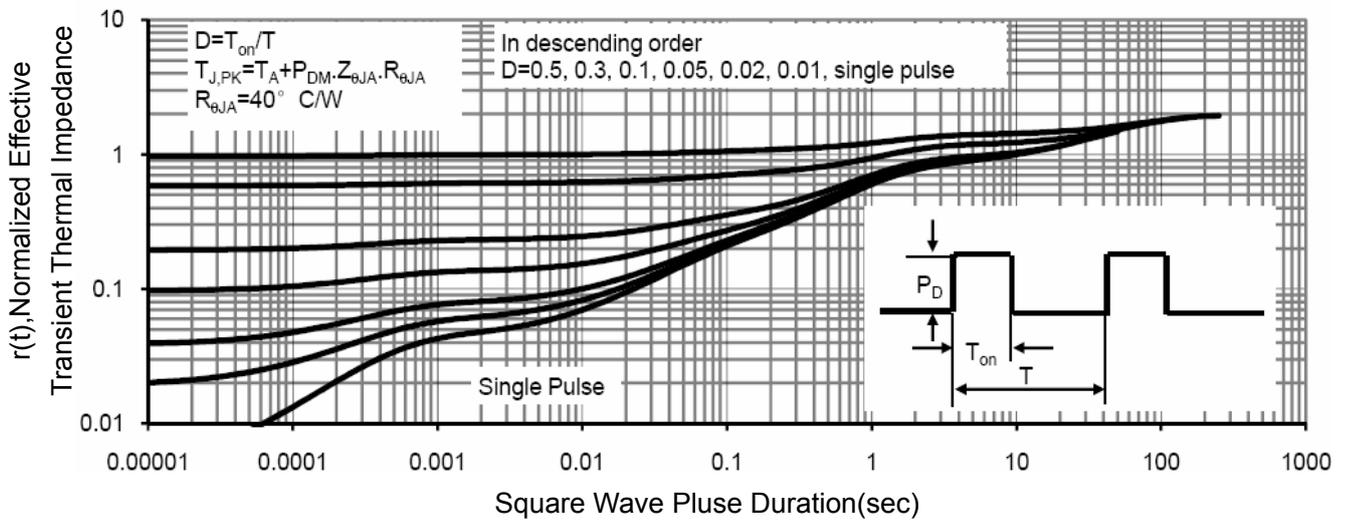
**Figure 9 BV<sub>DSS</sub> vs Junction Temperature**



**Figure 8 Safe Operation Area**

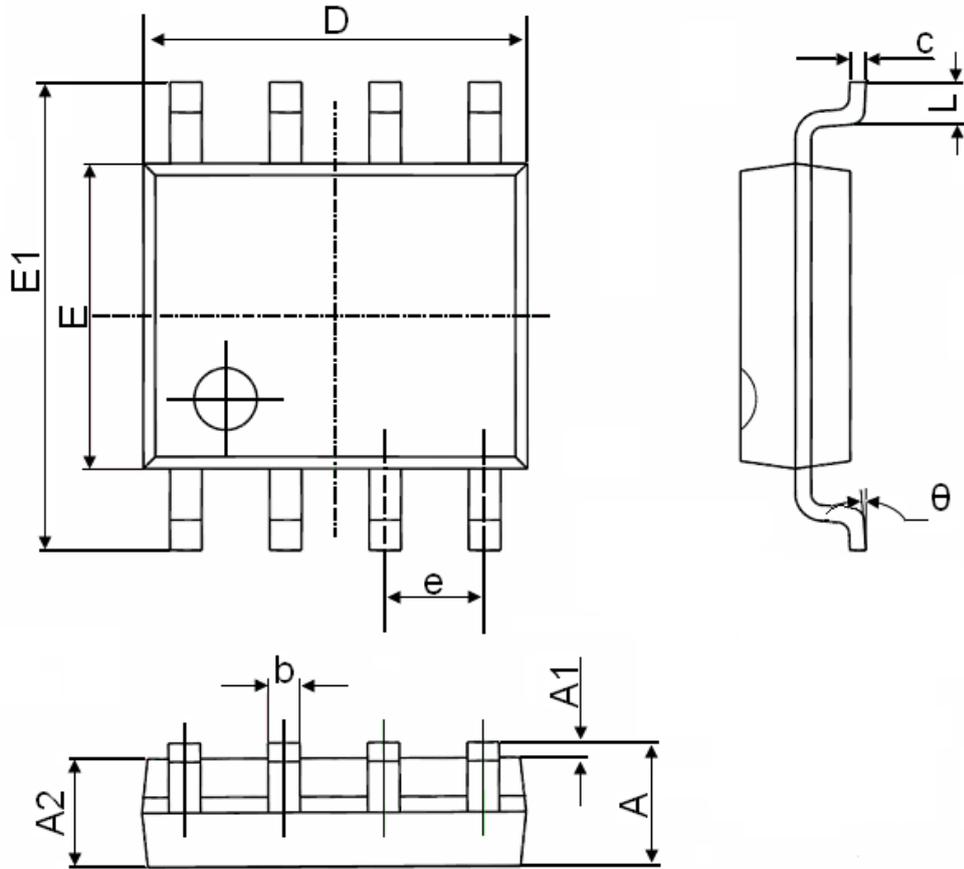


**Figure 10 V<sub>GS(th)</sub> vs Junction Temperature**



**Figure 11 Normalized Maximum Transient Thermal Impedance**

## SOP-8 Package Information



| Symbol | Dimensions In Millimeters |       | Dimensions In Inches |       |
|--------|---------------------------|-------|----------------------|-------|
|        | Min.                      | Max.  | Min.                 | Max.  |
| A      | 1.350                     | 1.750 | 0.053                | 0.069 |
| A1     | 0.100                     | 0.250 | 0.004                | 0.010 |
| A2     | 1.350                     | 1.550 | 0.053                | 0.061 |
| b      | 0.330                     | 0.510 | 0.013                | 0.020 |
| c      | 0.170                     | 0.250 | 0.006                | 0.010 |
| D      | 4.700                     | 5.100 | 0.185                | 0.200 |
| E      | 3.800                     | 4.000 | 0.150                | 0.157 |
| E1     | 5.800                     | 6.200 | 0.228                | 0.244 |
| e      | 1.270(BSC)                |       | 0.050(BSC)           |       |
| L      | 0.400                     | 1.270 | 0.016                | 0.050 |
| theta  | 0°                        | 8°    | 0°                   | 8°    |